

TECHNICAL SPECIFICATION		
Features	Units	Available planes
		C-plane (0001)
Carrier concentration	cm ⁻³	-
Dopant		Manganese-doped ($\sim 10^{19}$ cm ⁻³)
Resistivity	Ω cm	$>10^9$
Mobility	cm ² /Vs	-
Thickness	μ m	300-400 \pm 50
TTV	μ m	≤ 40
Bow	μ m	≤ 10
FWHM (0002) of XRC, (epi-ready; 0.1x0.1 mm slit)	arcsec	~ 20
Etch Pits Density (EPD)	cm ⁻²	$\sim 5 \times 10^4$
Off-cut	deg	0.3 \pm 0.1 to the m-direction
Surface finishing	Front side	epi-ready (RMS < 0.5 nm)
	Back side	rough
Available sizes		10x10mm
		1-inch
		1.5-inch
Packaging		separate single wafer container
Special request		for pricing or technical enquiries please contact our sales team

Round shape

